

0.5A High-Speed MOSFET Drivers

Features

- Latch-Up Protected: Will Withstand 500 mA Reverse Current
- Input Will Withstand Negative Inputs Up to 5V
- · ESD Protected: 4 kV
- High Peak Output Current: 0.5A
- Wide Input Supply Voltage Operating Range:
 4.5V to 16V
- High Capacitive Load Drive Capability:
 - 500 pF in 25 nsec
- Short Delay Time: 30 nsec Typ.
- Consistent Delay Times With Changes in Supply Voltage
- · Matched Delay Times
- · Low Supply Current
 - With Logic '1' Input: 500 µA
 - With Logic '0' Input: 100 µA
- Low Output Impedance: 16Ω
- · Available in Space-Saving 8-pin MSOP Package
- Pinout Same as TC1411/TC1412/TC1413

Applications

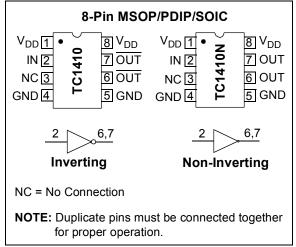
- · Switch Mode Power Supplies
- Line Drivers
- Pulse Transformer Drive
- Relay Driver

General Description

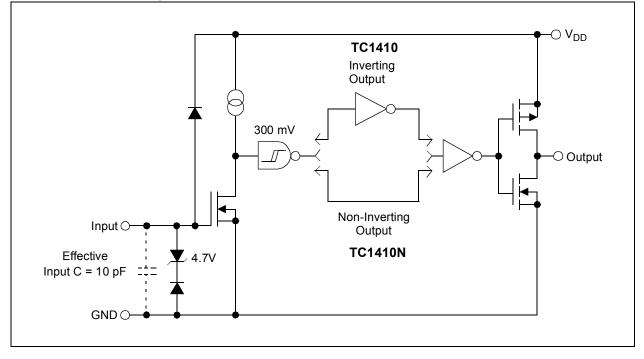
The TC1410/TC1410N are 0.5A CMOS buffers/drivers. They will not latch-up under any conditions within their power and voltage ratings. They are not subject to damage when up to 5V of noise spiking of either polarity occurs on the ground pin. They can accept, without damage or logic upset, up to 500 mA of current of either polarity being forced back into their output. All terminals are fully protected against up to 4 kV of electrostatic discharge.

As MOSFET drivers, the TC1410/TC1410N can easily charge a 500 pF gate capacitance in 25 nsec with matched rise and fall times, and provide low enough impedance in both the 'ON' and 'OFF' states to ensure the MOSFET's intended state will not be affected, even by large transients. The leading and trailing edge propagation delay times are also matched to allow driving short-duration inputs with greater accuracy.

Package Type



Functional Block Diagram



1.0 **ELECTRICAL CHARACTERISTICS**

Absolute Maximum Ratings †

Supply Voltage+20V
Input Voltage V_{DD} + 0.3V to GND – 5.0V
Power Dissipation $(T_A \le 70^{\circ}C)$
MSOP
PDIP
SOIC
Storage Temperature Range65°C to +150°C
Maximum Junction Temperature +150°C

+ Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

PIN FUNCTION TABLE

Symbol	Description
V _{DD}	Supply input, 4.5V to 16V
INPUT	Control input
NC	No connection
GND	Ground
GND	Ground
OUTPUT	CMOS push-pull output, common to pin 7
OUTPUT	CMOS push-pull output, common to pin 6
V _{DD}	Supply input, 4.5V to 16V

Parameters	Sym	Min	Тур	Мах	Units	Conditions
Input				•	•	·
Logic '1', High Input Voltage	V _{IH}	2.0	_	_	V	
Logic '0', Low Input Voltage	V _{IL}	—		0.8	V	
Input Current	I _{IN}	-1	_	1	μA	$0V \le V_{IN} \le V_{DD}, T_A = +25^{\circ}C$
		-10	—	10		$-40^{\circ}C \leq T_{A} \leq +85^{\circ}C$
Output						
High Output Voltage	V _{OH}	V _{DD} – 0.025	_	—	V	DC Test
Low Output Voltage	V _{OL}	—		0.025	V	DC Test
Output Resistance	R _O	—	16	22	Ω	V _{DD} = 16V, I _O = 10 mA, T _A = +25°C
		—	20	28		$0^{\circ}C \leq T_{A} \leq +70^{\circ}C$
		—	20	28		$-40^{\circ}C \leq T_{A} \leq +85^{\circ}C$
Peak Output Current	I _{PK}	—	0.5	_	Α	V _{DD} = 16V
Latch-Up Protection Withstand Reverse Current	I _{REV}	_	0.5	—	A	Duty cycle \leq 2%, t \leq 300 µsec, V _{DD} = 16V
Switching Time (Note 1)		•		•		•
Rise Time	t _R	—	25	35	nsec	T _A = +25°C
		_	27	40		$0^{\circ}C \leq T_{A} \leq +70^{\circ}C$

		—	27	40		$0^{\circ}C \leq T_{A} \leq +70^{\circ}C$
		—	29	40		-40°C \leq T _A \leq +85°C, Figure 4-1
Fall Time	t _F	—	25	35	nsec	T _A = +25°C
		—	27	40		$0^{\circ}C \leq T_{A} \leq +70^{\circ}C$
		—	29	40		-40°C \leq T _A \leq +85°C, Figure 4-1
Delay Time	t _{D1}	_	30	40	nsec	T _A = +25°C
			33	45		$0^{\circ}C \leq T_{A} \leq +70^{\circ}C$
		—	35	45		-40°C \leq T _A \leq +85°C, Figure 4-1

Note 1: Switching times ensured by design.

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DC ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise noted, over operating temperature range with $4.5V \le V_{DD} \le 16V$. Typical values are measured at T _A = +25°C, V _{DD} = 16V.								
Parameters Sym Min Typ Max Units Conditions								
Delay Time	t _{D2}	_	30	40	nsec	T _A = +25°C		
		—	33	45		$0^{\circ}C \leq T_{A} \leq +70^{\circ}C$		
		—	35	45		-40°C ≤ T _A ≤ +85°C, Figure 4-1		
Power Supply	•			•				
Power Supply Current	۱ _S	_	0.5	1.0	mA	V _{IN} = 3V, V _{DD} = 16V		
		—	0.1	0.15		V _{IN} = 3V, V _{DD} = 16V V _{IN} = 0V		

Note 1: Switching times ensured by design.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with $4.5V \le V_{DD} \le 16V$.										
Parameters	Sym	Min	Тур	Мах	Units	Conditions				
Temperature Ranges										
Specified Temperature Range (C)	T _A	0	—	+70	°C					
Specified Temperature Range (E)	T _A	-40	—	+85	°C					
Maximum Junction Temperature	TJ	—	—	+150	°C					
Storage Temperature Range	T _A	-65	—	+150	°C					
Package Thermal Resistances										
Thermal Resistance, 8L-MSOP	θ_{JA}	—	206		°C/W					
Thermal Resistance, 8L-PDIP	θ_{JA}	_	125		°C/W					
Thermal Resistance, 8L-SOIC	θ_{JA}	—	155	—	°C/W					

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, over operating temperature range with 4.5V \leq V_{DD} \leq 16V.

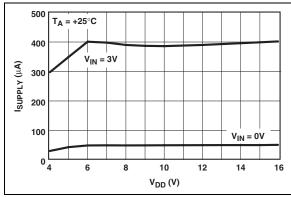


FIGURE 2-1: Quiescent Supply Current vs. Supply Voltage.

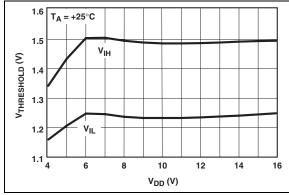


FIGURE 2-2: Input Threshold vs. Supply Voltage.

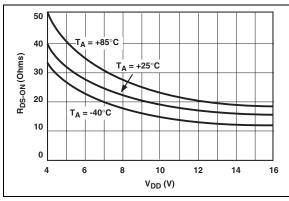


FIGURE 2-3: High-State Output Resistance vs. Supply Voltage.

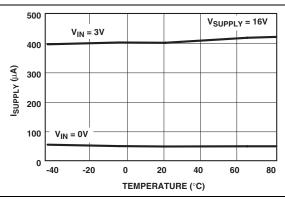


FIGURE 2-4: Quiescent Supply Current vs. Temperature.

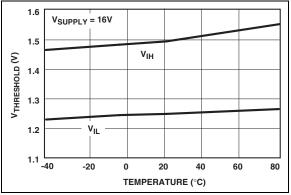


FIGURE 2-5: Temperature.

Input Threshold vs.

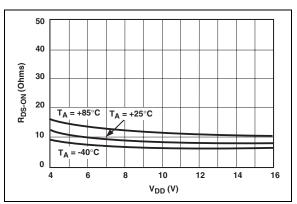
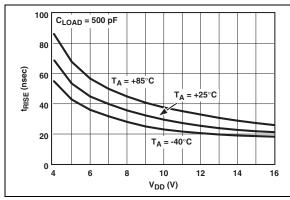
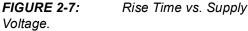


FIGURE 2-6: Low-State Output Resistance vs. Supply Voltage.

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Note: Unless otherwise indicated, over operating temperature range with 4.5V \leq V_{DD} \leq 16V.





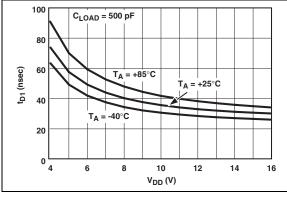


FIGURE 2-8: Supply Voltage.

Propagation Delay vs.

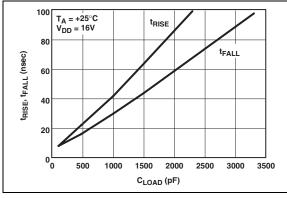


FIGURE 2-9: Rise and Fall Times vs. Capacitive Load.

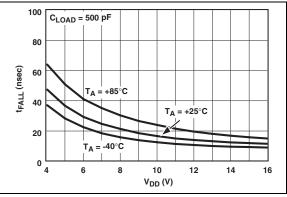


FIGURE 2-10: Fall Time vs. Supply Voltage.

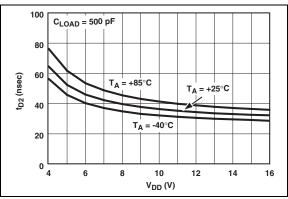


FIGURE 2-11: Propagation Delay vs. Supply Voltage.

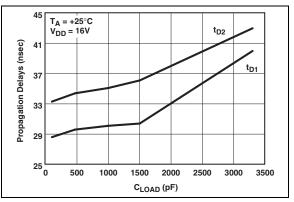


FIGURE 2-12: Propagation Delays vs. Capacitive Load.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

		· · · · · · · · · · · · · · · · · · ·
Pin No.	Symbol	Description
1	V _{DD}	Supply input, 4.5V to 16V
2	INPUT	Control input
3	NC	No connection
4	GND	Ground
5	GND	Ground
6	OUTPUT	CMOS push-pull output, common to pin 7
7	OUTPUT	CMOS push-pull output, common to pin 6
8	V_{DD}	Supply input, 4.5V to 16V

TABLE 3-1: PIN FUNCTION TABLE

3.1 Supply Input (V_{DD})

The V_{DD} input is the bias supply for the MOSFET driver and is rated for 4.5V to 16V with respect to the ground pin. The V_{DD} input should be bypassed to ground with a local ceramic capacitor. The value of the capacitor should be chosen based on the capacitive load that is being driven. A value of 1.0 μ F is suggested.

3.2 Control Input (INPUT)

The MOSFET driver input is a high-impedance, TTL/CMOS-compatible input. The input also has 300 mV of hysteresis between the high and low thresholds that prevents output glitching even when the rise and fall time of the input signal is very slow.

3.3 CMOS Push-Pull Output (OUTPUT)

The MOSFET driver output is a low-impedance, CMOS, push-pull style output, capable of driving a capacitive load with 0.5 A peak currents.

3.4 Ground

The ground pins are the return path for the bias current and for the high peak currents that discharge the load capacitor. The ground pins should be tied into a ground plane or have very short traces to the bias supply source return.

4.0 APPLICATIONS INFORMATION

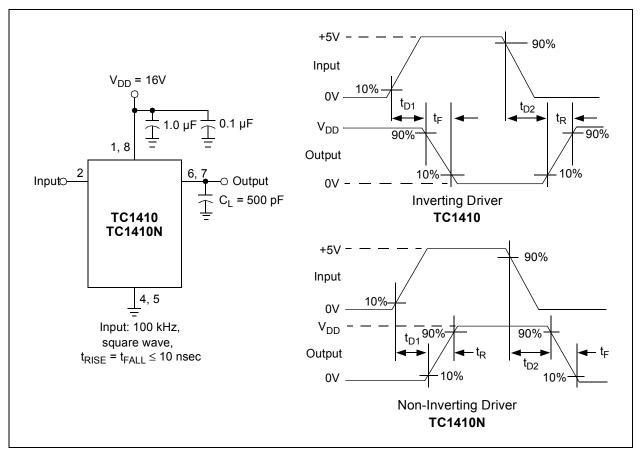
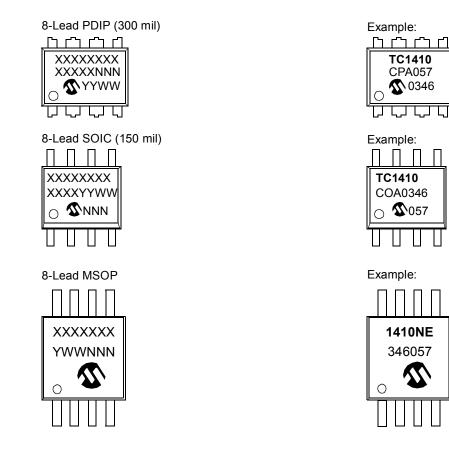


FIGURE 4-1: Switching Time Test Circuit.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

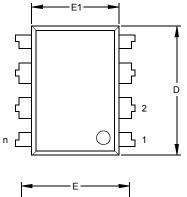


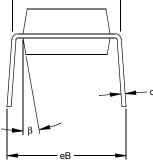
Legend	: XXX YY WW NNN	Customer specific information* Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code
Note:	be carried	nt the full Microchip part number cannot be marked on one line, it will over to the next line thus limiting the number of available characters er specific information.

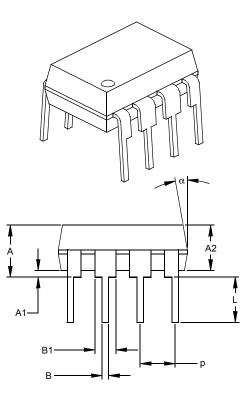
* Standard marking consists of Microchip part number, year code, week code, traceability code (facility code, mask rev#, and assembly code). For marking beyond this, certain price adders apply. Please check with your Microchip Sales Office.

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8-Lead Plastic Dual In-line (PA) – 300 mil (PDIP)







	Units		INCHES*		N	IILLIMETERS	6
Dimensio	n Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

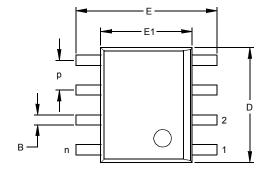
* Controlling Parameter § Significant Characteristic

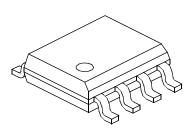
Notes:

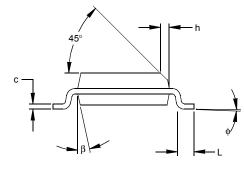
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-001

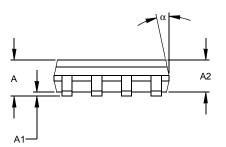
Drawing No. C04-018

8-Lead Plastic Small Outline (OA) - Narrow, 150 mil (SOIC)









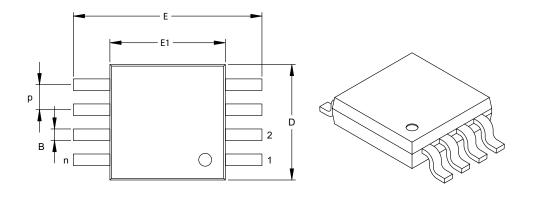
	Units	INCHES*			MILLIMETERS		
Dimensi	on Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.050			1.27	
Overall Height	Α	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	Е	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	¢	0	4	8	0	4	8
Lead Thickness	С	.008	.009	.010	0.20	0.23	0.25
Lead Width	В	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

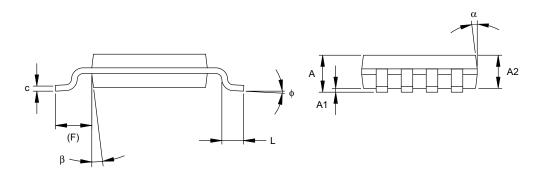
* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-012 Drawing No. C04-057

8-Lead Plastic Micro Small Outline Package (UA) (MSOP)





	Units		INCHES		M	ILLIMETERS'	ŧ
Dimension L	imits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.026 BSC			0.65 BSC	
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E		.193 TYP.		4.90 BSC		
Molded Package Width	E1		.118 BSC		3.00 BSC		
Overall Length	D		.118 BSC		3.00 BSC		
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F		.037 REF	•		0.95 REF	
Foot Angle	φ	0°	-	8°	0°	-	8°
Lead Thickness	С	.003	.006	.009	0.08	-	0.23
Lead Width	В	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°
*Controlling Donous stor							

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187 Drawing No. C04-111

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>× /××</u>	Exa	Examples:				
Device	Femperature Package Range	a)	TC1410COA:	0.5A Single MOSFET driver, SOIC package, 0°C to +70°C.			
Device:	TC1410: 0.5A Single MOSFET Driver, Inverting TC1410N: 0.5A Single MOSFET Driver, Non-Inverting	b)	TC1410CPA:	0.5A Single MOSFET driver, PDIP package, 0°C to +70°C.			
Temperature Range:	$C = 0^{\circ}C \text{ to } +70^{\circ}C$ E = -40^{\circ}C to +85^{\circ}C	c)	TC1410EUA713:	Tape and Reel, 0.5A Single MOSFET driver, MSOP package, -40°C to +85°C.			
Package:	 OA = Plastic SOIC, (150 mil Body), 8-lead OA713 = Plastic SOIC, (150 mil Body), 8-lead (Tape and Reel) UA = Plastic Micro Small Outline (MSOP), 8-lead * UA713 = Plastic Micro Small Outline (MSOP), 8-lead * 	a)	TC1410NCPA:	0.5A Single MOSFET driver, PDIP package, 0°C to +70°C.			
	(Tape and Reel) PA = Plastic DIP (300 mil Body), 8-lead * MSOP package is only available in E-Temp.	b)	TC1410NEPA:	0.5A Single MOSFET driver, PDIP package, -40°C to +85°C.			
		c)	TC1410NEUA:	0.5A Single MOSFET driver, MSOP package, -40°C to +85°C.			

Sales and Support

Data Sheets

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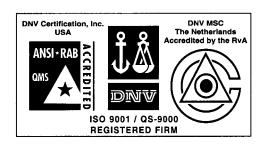
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